

SOLDER ALLOY FOR BONDING CU PIPES AND/OR FE PIPES, PREFORM SOLDER, RESIN FLUX  
CORED SOLDER, AND SOLDER JOINT

ABSTRACT

Provided is a solder alloy that makes it possible to ensure long-term bonding reliability in metal piping by minimizing the growth of an intermetallic compound layer at the bonding interface when performing low-temperature bonding of metal piping. This solder alloy comprises, in mass%, 5.0-15.0% of Sb, 0.5-8.0% of Cu, 0.025-0.7% of Ni, 0.025-0.3% of Co, and a remainder of Sn. The content (in mass%) of Co and Ni in the alloy composition of the solder alloy satisfies  $0.07 \leq \text{Co/Ni} \leq 6$ .

[FIG. 5]